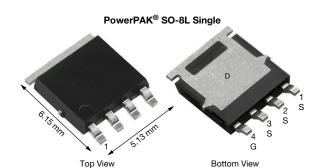
# Vishay Siliconix

# N-Channel 80 V (D-S) MOSFET



PRODUCT SUMMARY							
V <sub>DS</sub> (V)	80						
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 10 \text{ V}$	0.0062						
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 7.5 \text{ V}$	0.0065						
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$	0.0095						
Q <sub>g</sub> typ. (nC)	24						
I <sub>D</sub> (A) <sup>a, g</sup>	60						
Configuration	Single						

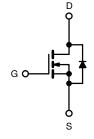
#### **FEATURES**

- TrenchFET® power MOSFET
- 100 % R<sub>g</sub> and UIS tested
- Capable of operating with 5 V gate drive
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



#### **APPLICATIONS**

- DC/DC primary side switch
- · Synchronous rectification
- · High current switching



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SiJ482DP-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V <sub>DS</sub>	80	V	
Gate-source voltage		V <sub>GS</sub>	± 20		
	T <sub>C</sub> = 25 °C		<b>60</b> <sup>g</sup>		
Continuous drain current (T. – 150 °C)	T <sub>C</sub> = 70 °C	1_	60 <sup>g</sup>		
Continuous drain current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	21.1 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		16.9 <sup>b, c</sup>	$\exists$	
Pulsed drain current (t = 300 μs)	I <sub>DM</sub>	100	A		
Continuous source-drain diode current	T <sub>C</sub> = 25 °C		60 <sup>g</sup>		
	T <sub>A</sub> = 25 °C	I <sub>S</sub>	4.5 b, c		
Single pulse avalanche current		I <sub>AS</sub>	30		
Single pulse avalanche energy	L = 0.1 mH	E <sub>AS</sub>	45	mJ	
	T <sub>C</sub> = 25 °C		69.4		
Maximum power dissipation	T <sub>C</sub> = 70 °C		44.4	w	
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	5 b, c		
	T <sub>A</sub> = 70 °C		3.2 b, c		
Operating junction and storage temperature ra	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C		
Soldering recommendations (peak temperature	e) <sup>d, e</sup>	, and the second	260		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient b, f	t ≤ 10 s	R <sub>thJA</sub>	20	25	°C/W
Maximum junction-to-case (drain)	Steady state	$R_{thJC}$	1.3	1.8	C/VV

#### **Notes**

- a. Based on  $T_C$  = 25 °C b. Surface mounted on 1" x 1" FR4 board
- See solder profile (<a href="https://www.vishay.com/doc?73257">www.vishay.com/doc?73257</a>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 65 °C/W
- Package limited

# Vishay Siliconix

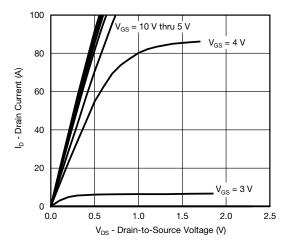
SPECIFICATIONS (T <sub>J</sub> = 25 °C, t	unless otherv	wise noted)					
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	80	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	. OFO A	-	36	-	) //00	
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-5.7	-	mV/°C	
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.5	-	2.7	V	
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
Zava gata valtaga duain avuunnt		V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V		1			
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	-	-	10	μA	
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30	-	-	Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A	-	0.0051	0.0062		
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 7.5 V, I <sub>D</sub> = 15 A	-	0.0054	0.0065	Ω	
		$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	-	0.0068	0.0095		
Forward transconductance a	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 20 A	-	68	-	S	
Dynamic <sup>b</sup>							
Input capacitance	C <sub>iss</sub>		-	2425	-		
Output capacitance	C <sub>oss</sub>	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	1180	-	pF		
Reverse transfer capacitance	C <sub>rss</sub>		-	100	-		
Total gate charge	Qg	$V_{DS} = 40 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	47	71		
		$V_{DS} = 40 \text{ V}, V_{GS} = 7.5 \text{ V}, I_D = 10 \text{ A}$	-	36.5	55	7	
			-	24	36	nC	
Gate-source charge	$Q_{gs}$	$V_{DS} = 40 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	-	6.6	-		
Gate-drain charge	$Q_{gd}$		-	10.2	-		
Output charge	Q <sub>oss</sub>	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$	-	69	105		
Gate resistance	$R_g$	f = 1 MHz	0.4	1.1	2.2	Ω	
Turn-on delay time	t <sub>d(on)</sub>		-	14	28		
Rise time	t <sub>r</sub>	$V_{DD} = 40 \text{ V}, R_L = 4 \Omega$	-	11	22		
Turn-off delay time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	36	72		
Fall time	t <sub>f</sub>		-	9	18	ns	
Turn-on delay time	t <sub>d(on)</sub>		-	16	32		
Rise time	t <sub>r</sub>	$V_{DD} = 40 \text{ V}, R_L = 4 \Omega$	-	13	26		
Turn-off delay time	t <sub>d(off)</sub>	$I_D\cong 10$ A, $V_{GEN}=7.5$ V, $R_g=1$ $\Omega$	-	35	70		
Fall time	t <sub>f</sub>			11	22		
<b>Drain-Source Body Diode Characteristi</b>	cs						
Continuous source-drain diode current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	60	^	
Pulse diode forward current <sup>a</sup>	I <sub>SM</sub>		-	-	100	A	
Body diode voltage	V <sub>SD</sub>	I <sub>S</sub> = 4 A	-	0.73	1.1	V	
Body diode reverse recovery time	t <sub>rr</sub>		-	46	90	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	44	86	nC	
Reverse recovery fall time	t <sub>a</sub>	T <sub>J</sub> = 25 °C	-	21	-	<b>n</b> -	
Reverse recovery rise time	t <sub>b</sub>		-	25	-	ns	

#### Notes

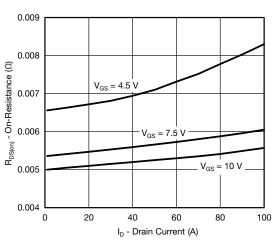
- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

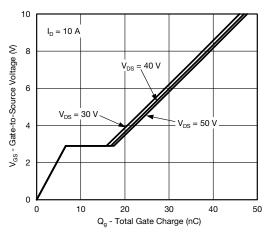




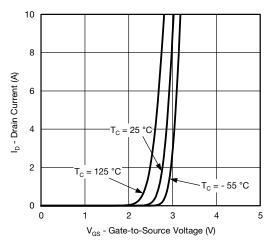
#### **Output Characteristics**



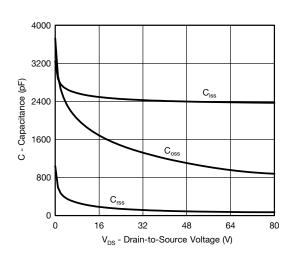
On-Resistance vs. Drain Current and Gate Voltage



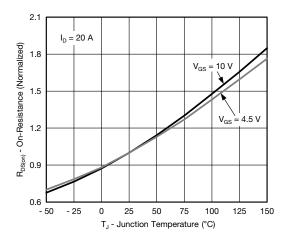
Gate Charge



**Transfer Characteristics** 

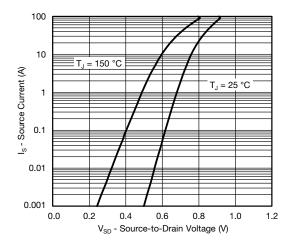


Capacitance

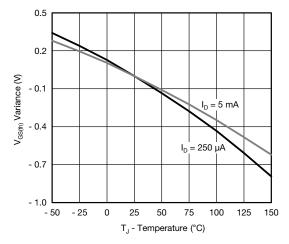


On-Resistance vs. Junction Temperature

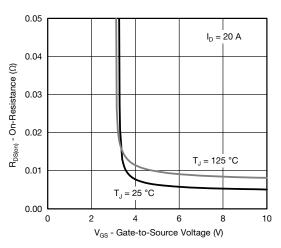




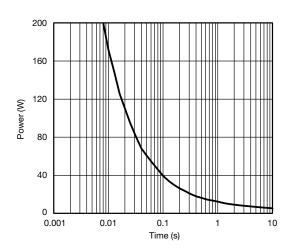
### Source-Drain Diode Forward Voltage



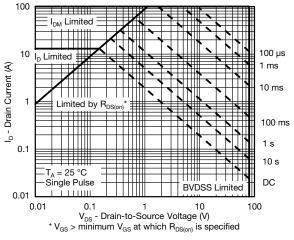
**Threshold Voltage** 



On-Resistance vs. Gate-to-Source Voltage

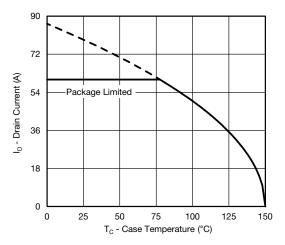


Single Pulse Power, Junction-to-Ambient

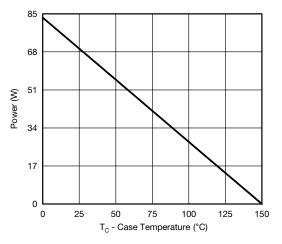


Safe Operating Area, Junction-to-Ambient

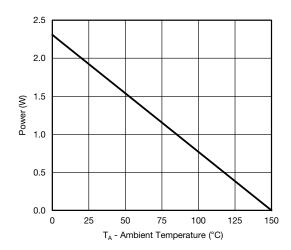




#### Current Derating a





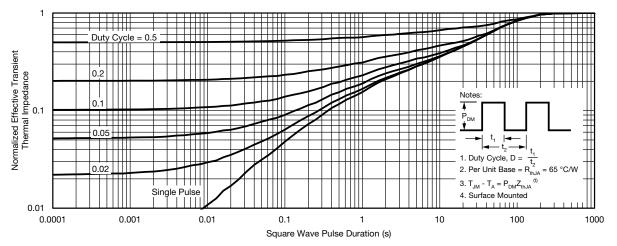


Power, Junction-to-Ambient

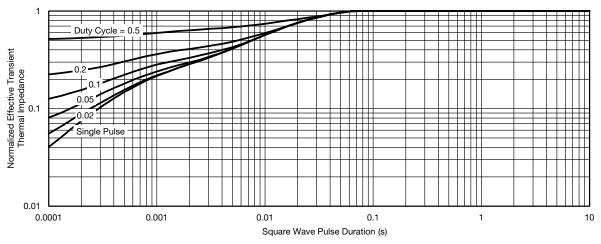
### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient

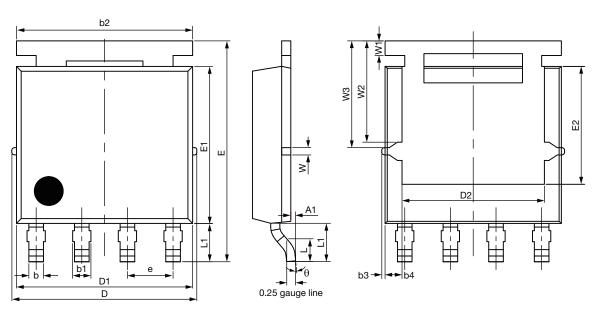


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?63728">www.vishay.com/ppg?63728</a>.

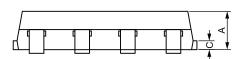


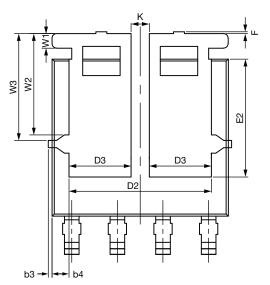
# PowerPAK® SO-8L Case Outline 1



Topside view

Backside view (single)





Backside view (dual)



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DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094	•		0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC	•	0.050 BSC			
E	6.05	6.15	6.25	0.238	0.238 0.242 0		
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	3.18	3.28	3.38	0.125	0.129	0.133	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51			0.020		
W	0.23			0.009			
W1	0.41			0.016			
W2	2.82			0.111			
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

ECN: S19-0643-Rev. E, 05-Aug-2019

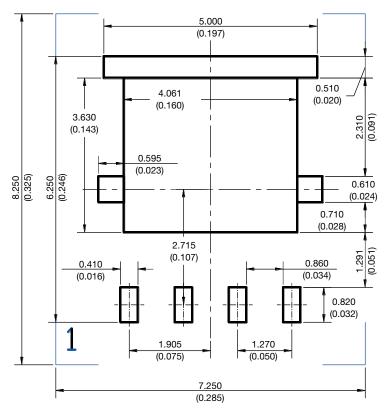
DWG: 5976

#### Note

• Millimeters will gover



### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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Vishay

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